



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification Number:	20260831000.0	Notification Issued	August 31, 2026
MSL Update for Select Device			

Change Type(s)	Packing/Shipping/Labeling
ZVEI ID	SEM-PS-02

Notification Details

Description of Change:		
This Notification is to inform of a change to the MSL ratings for the device listed below as follows:		

Products Affected:		
LM34936QPWPRQ1	LM5176QPWPRQ1	TPS55165QPWPTQ1
LM34936QPWPTQ1	LM5176QPWPTQ1	TPS61175QPWPRQ1
LM34966QPWPRQ1	TPS55162QPWPRQ1	TPS7B6833QPWPRQ1
LM5175QPWPRQ1	TPS55162QPWPTQ1	TPS7B6850QPWPRQ1
LM5175QPWPTQ1	TPS55165QPWPRQ1	TPS7B7702QPWPRNP

Qualification Report

Automotive Qualification Summary (As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 05-August-2026

Product Attributes

Attributes	Qual Device:	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:
	TPS54612QPWPRQ1	TIC12400QDCPRQ1	TIC12400QDCPRQ1	LP8880DCPRQ1	TPS65140IPWPRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Interface,Signal Chain	Interface,Signal Chain	Power Management	Signal Chain
Wafer Fab Supplier	DL-LIN	RFAB	RFAB	RFAB	DL-LIN
Assembly Site	TAI	TAI	TAI	TAI	TAI
Package Group	TSSOP	TSSOP	TSSOP	TSSOP	TSSOP
Package Designator	PWP	DCP	DCP	DCP	PWP
Pin Count	28	38	38	38	24

QBS: Qual By Similarity, also known as Generic Data
Qual Device TPS54612QPWPRQ1 is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device:	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:
								TPS54612QPWPRQ1	TIC12400QDCPRQ1	TIC12400QDCPRQ1	LP8880DCPRQ1	TPS65140IPWPRQ1
Test Group A - Accelerated Environment Stress Tests												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	3/630/0	-	-	-	3/864/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	1/Pass	2/Pass	3/Pass	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	2/154/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	1/77/0	-	3/231/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	130C/85%RH	96 Hours	-	-	2/154/0	-	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/261/0	1/77/0	2/154/0	3/231/0	-
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	1/5/0	-	-	-
PTC	A5	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	-	-	1/45/0	1/45/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	3/138/0	1/45/0	2/90/0	3/135/0	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	1/77/0	1/77/0	1/77/0	-

ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	2/1600/0	-	-
EDR	B3	AEC Q100-005	1	77	NVM Endurance, Data Retention, and Op Life	Per QSS-009-018	1 Step	-	1/77/0	1/77/0	-	-
Test Group C - Package Assembly Integrity Tests												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	1/30/0	1/30/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	1/30/0	1/30/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	1/15/0	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	1/10/0	1/10/0	3/30/0	3/30/0
Test Group E - Electrical Verification Tests												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	-	1/3/0	-
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	3000 Volts	-	1/3/0	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1000 Volts	-	1/3/0	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	-	1/3/0	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-	1/6/0	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	3/90/0	-	3/90/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2412-036

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